



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventors: Jian Zhou; Hua Chu  
Assignee: Nanometrics Incorporated  
Title: Method for Automatically De-Skewing of Multiple Layer Wafer for Improved Pattern Recognition  
Serial No.: 09/974,721 Filing Date: October 9, 2001  
Examiner: Colin M. Larose Group Art Unit: 1765  
Docket No.: NAN050 US Confirmation No.: 7841

Santa Clara, California  
March 22, 2006

Mail Stop Amendment  
Commissioner For Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

## **RESPONSE TO OFFICE ACTION**

Dear Sir:

This Response to Office Action is responsive to the December 19, 2005, Office Action, which has a statutorily shortened period for response that ends March 19, 2006. A petition for a one month extension is attached hereto giving Applicant until April 19, 2006, to respond. Please enter the following amendments before taking action on the merits of the above-referenced application.

SILICON VALLEY  
PATENT GROUP LLP

2350 Mission College Blvd.  
Suite 360  
Santa Clara, CA 95054  
(408) 982-8200  
FAX (408) 982-8210